

CLAIM AMENDMENTS

The following listing of the claims replaces all prior versions, and listings, of the claims in the application.

1. (Currently Amended) An apparatus, comprising:
a base;

a device connected to the base; and

a cover including a one-piece plastic body and at least one electrically conductive lead,
wherein the body overlaps but is not directly connected to the base such that the device is enclosed by the body, and wherein the electrically conductive lead includes an exposed portion electrically connected to the device.
2. (Original) The apparatus of claim 1, wherein an inner surface of the body of the cover and an upper surface of the device define an air gap therebetween.
3. (Original) The apparatus of claim 2, wherein the inner surface of the body of the cover includes a sidewall connected to the base.
4. (Original) The apparatus of claim 1, wherein the base includes an electrically conductive baseplate on which the device is mounted.

5. (Original) The apparatus of claim 1, wherein the base includes a substrate on which the device is fabricated.
6. (Original) The apparatus of claim 5, further comprising:
at least one electrically conductive via extending from a first surface of the substrate to a second surface of the substrate; and
at least one electrically conductive ball connected to the electrically conductive via.
7. (Original) The apparatus of claim 1, wherein the base includes a dielectric material.
8. (Original) The apparatus of claim 1, further comprising an electrically conductive bump between the exposed portion of the lead and the device.
9. (Original) The apparatus of claim 1, wherein the body of the cover includes liquid crystal polymer.
10. (Original) The apparatus of claim 1, wherein the device includes a semiconductor device.

11. (Original) The apparatus of claim 10, wherein the semiconductor device is selected from the group consisting of an integrated circuit, an RF device, and a microwave device.

12. (Original) The apparatus of claim 1, wherein the device includes a MMIC.

13. (Original) The apparatus of claim 1, wherein the device is selected from the group consisting of a MEMS device, an optoelectronic device, a crystal device, an acoustic wave device, and a capacitor.

14. (Currently Amended) An apparatus, comprising:
a base;
a device connected to the base;
a cover including a one-piece plastic body and at least one electrically conductive lead, wherein the body overlaps but is not directly connected to the base such that the device is enclosed by the body such that an inner surface of the body of the cover and an upper surface of the device define an air gap therebetween, and wherein the electrically conductive lead includes an exposed portion; and
an electrically conductive bump electrically connected between the device and the exposed portion of the electrically conductive lead.

15. (Currently Amended) An apparatus, comprising:
- an electrically conductive baseplate;
- a device connected to the baseplate; and
- a cover including a one-piece plastic body and at least one electrically conductive lead,
- wherein the body overlaps but is not directly connected to the baseplate such that the device is enclosed by the body, and wherein the electrically conductive lead includes an exposed portion electrically connected to the device via an electrically conductive bump.
16. (Original) The apparatus of claim 15, wherein the device includes a semiconductor device.
17. (Original) The apparatus of claim 16, wherein the semiconductor device is selected from the group consisting of an integrated circuit, an RF device, and a microwave device.
18. (Original) The apparatus of claim 15, wherein the device includes a MMIC.
- 19 (Original) The device of claim 15, wherein:
- the device includes a GaAs substrate; and
- the baseplate includes a metal selected from the group consisting of CuW and Cu/Mo/Cu.

20. (Original) The device of claim 19, wherein the body of the cover includes liquid crystal polymer.

21. (Original) The apparatus of claim 20, wherein an inner surface of the body of the cover and an upper surface of the device define an air gap therebetween.

22. (Original) The apparatus of claim 21, wherein the inner surface of the body of the cover includes a sidewall connected to the baseplate.

23-27. (Canceled)